

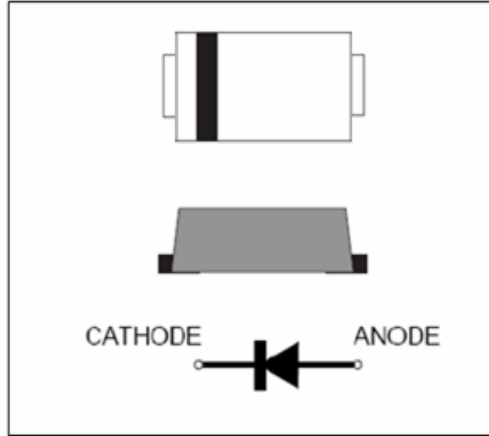
LMBR120LFT1G Thru LMBR160LFT1G

Schottky Barrier Rectifiers

Reverse Voltage 20 to 60V Forward Current 1.0A

FEATURES

- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- * Low power loss, high efficiency
- * For use in low voltage high frequency inverters, free wheeling, and polarity protection applications
- * Guardring for over voltage protection
- * High temperature soldering guaranteed: 260°C/10 seconds at terminals



We declare that the material of product is Halogen free (green epoxy compound)

Mechanical Data

Case: SOD123-FL/MINI SMA

molded plastic over sky die

Terminals: Tin Plated, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 0.0155 g

Handling precaution: None

1. Electrical Characteristic

Maximum & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR120LFT1G	LMBR140LFT1G	LMBR160LFT1G	Unit
device marking code		12L	14L	16L	
Maximum repetitive peak reverse voltage	V_{RRM}	20	40	60	V
Maximum RMS voltage	V_{RMS}	14	28	42	V
Maximum DC blocking voltage	V_{DC}	20	40	60	V
Maximum average forward rectified current at $T_C = 75^\circ\text{C}$	$I_{F(AV)}$	1.0			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30			A
Typical thermal resistance (Note 1)	$R_{\theta JA}$ $R_{\theta JC}$	110 40			$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55 to +125	-55 to +150		$^\circ\text{C}$
storage temperature range	T_{STG}	-65 to +150			$^\circ\text{C}$

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR120LFT1G	LMBR140LFT1G	LMBR160LFT1G	Unit
Maximum instantaneous forward voltage at ($I_F = 0.4\text{ A}$, $T_J = 25^\circ\text{C}$) ($I_F = 1.0\text{ A}$, $T_J = 25^\circ\text{C}$)	V_F	0.34 0.45	- 0.5	- 0.58	V
Maximum DC reverse current at rated DC blocking voltage $T_A = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	I_R	0.10 10	0.03 10		mA
Typical junction capacitance at 4.0V, 1MHz	C_J	160			PF

NOTES:

1. 8.0mm² (.013mm thick) land areas

LMBR120LFT1G Thru LMBR160LFT1G

2. Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

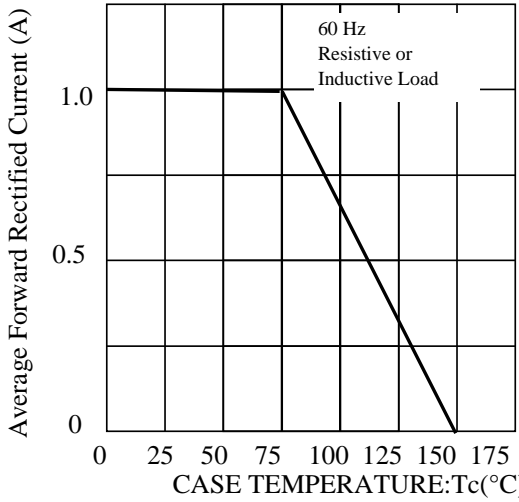


Fig. 2 - Maximum Non-repetitive Peak Forward Surge Current

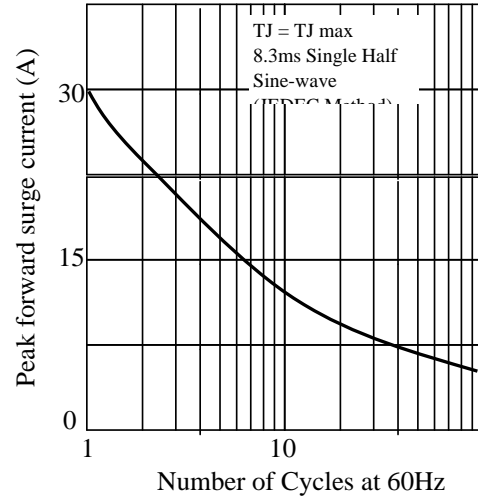


Fig. 3 - Typical Instantaneous Forward Characteristics

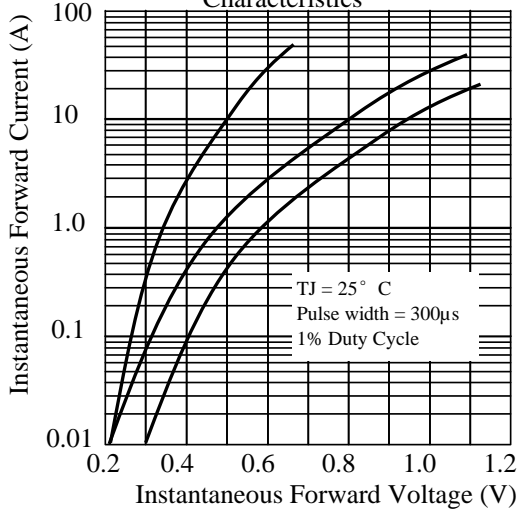


Fig. 4 - Typical Reverse Characteristics

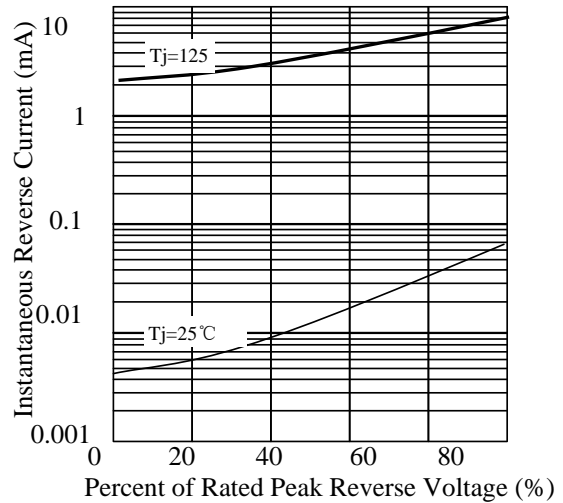


Fig. 5 - typical transient thermal impedance

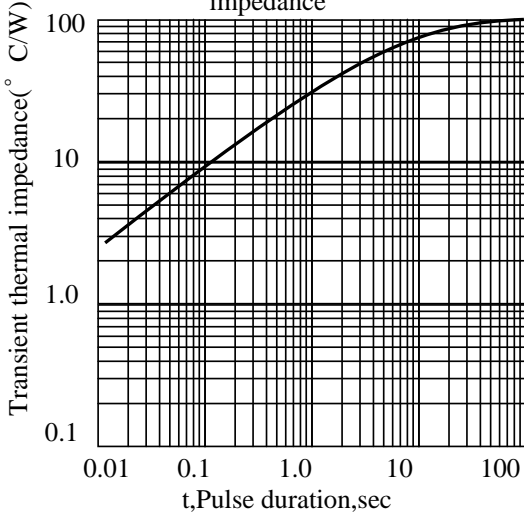
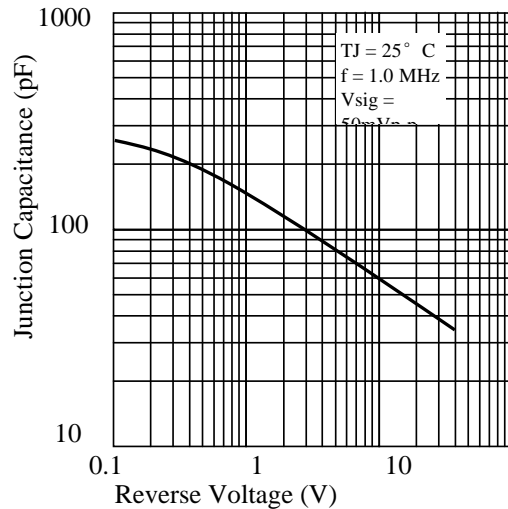


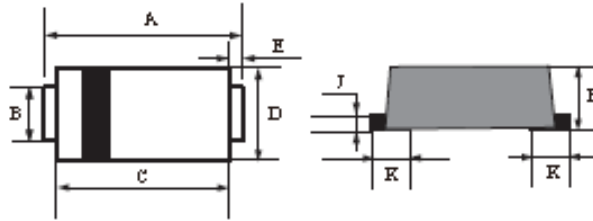
Fig. 6 - Typical Junction Capacitance



LMBR120LFT1G Thru LMBR160LFT1G

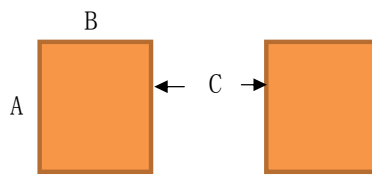
3. dimension:

SOD123-FL



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	3.5	3.9	0.138	0.159
B	0.75	0.95	0.029	0.037
C	2.6	3.0	0.103	0.119
D	1.6	2.0	0.063	0.079
E	0.45Typ		0.018Typ	
H	0.9	1.2	0.036	0.047
J	0.12	0.22	0.005	0.009
K	0.8Typ		0.032Typ	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD123-FL	0.044(1.10)	0.040(1.00)	0.079(2.00)

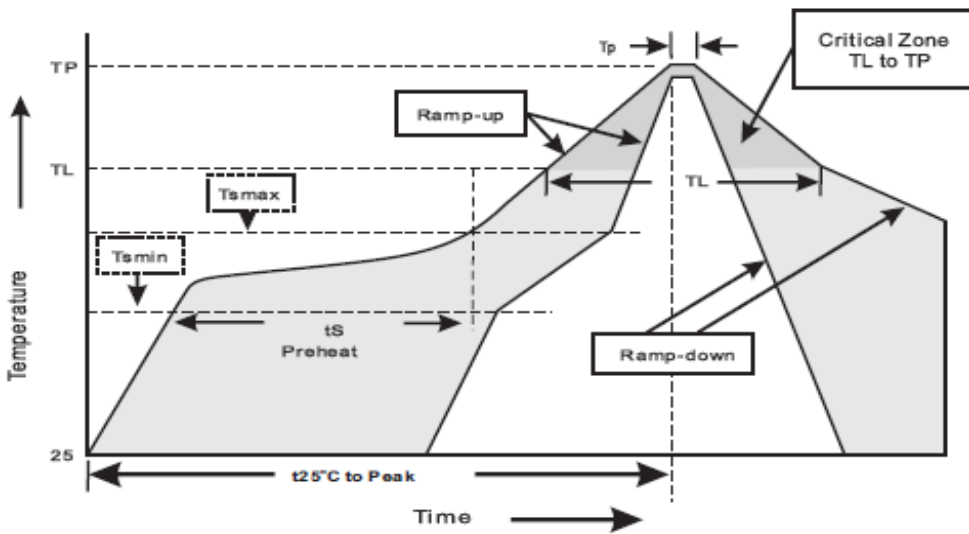
LMBR120LFT1G Thru LMBR160LFT1G

Reel packing

INNER BOX (mm)	REEL DIA. (mm)	CARTON SIZE (mm)	CARTON (PCS)	APPOX. GROSS WEIGHT (kg)
183*183*123	178	382*262*387	240,000	8.7

5.Suggested thermal profile for soldering process

1. Storage environment : Temperature=5~40°C Humidity=55±25%
2. Reflow soldering of surface-mount device



3. Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat	
- Temperature Min(T _{smin})	150°C
- Temperature Max(T _{smax})	200°C
- Time(min to max)(t _s)	60~120sec
T _{smax} to T _L	
- Ramp-up Rate	<3sec
Time maintained above:	
- Temperature (T _L)	217°C
- Time(t _L)	60-260sec
Peak Temperature(T _P)	255 -0/+5°C
Time within 5°C of actual Peak Temperature(T _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

LMBR120LFT1G Thru LMBR160LFT1G

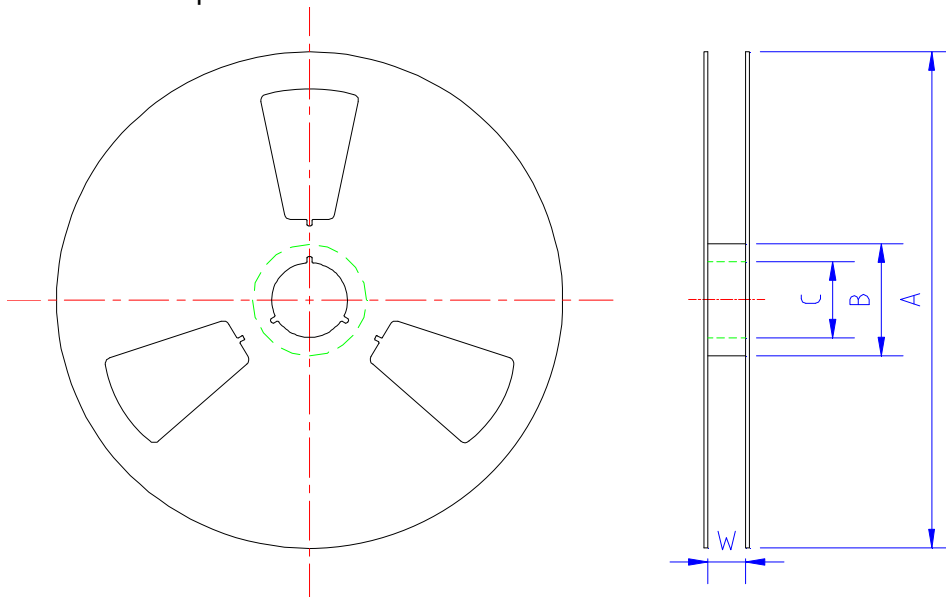
6.High reliability test capabilities

Item Test	Condition	Reference
Solder Resistance	at 260±5°C for 10±2sec immerse body into solder 1/16" ± 1/32"	MIL-STD-750D METHOD-2031
Solderability	at 245±5°C for 5 sec	MIL-STD-202F METHOD-208
High Temperature Reverse Bias	V _R =80% rate at T _j =150°C for 168hrs	MIL-STD-750D METHOD-1038
Forward Operation Life	Rated average rectifier current T _A =25°C for 500hrs	MIL-STD-750D METHOD-1027
Intermittent Operation Life	T _A =25°C , I _F =I _o On state:power on for 5 min. Off state:power off for 5 min. on and off for 500 cycles	MIL-STD-750D METHOD-1036
Pressure Cooker	15P _{SIG} at T _A =121°C for 4hrs	JESD22-A102
Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. Total 10 cycles	MIL-STD-750D METHOD-1051
Thermal Shock	0°C for 5min. Rise to 100°C for 5min. Total 10 cycles	MIL-STD-750D METHOD-1056
Forward Surge	8.3ms single half sine-wave superimposed on rated load,one surge	MIL-STD-750D METHOD-4066-2
Humidity	at T _A =85°C , RH=85% for 1000hrs	MIL-STD-750D METHOD-1021
High Temperature Storage Life	at 175°C for 1000hrs	MIL-STD-750D METHOD-1031

5.1 、 SMD Packing Reel Spec & Packing Quantity

5.1.1 Reel Packing

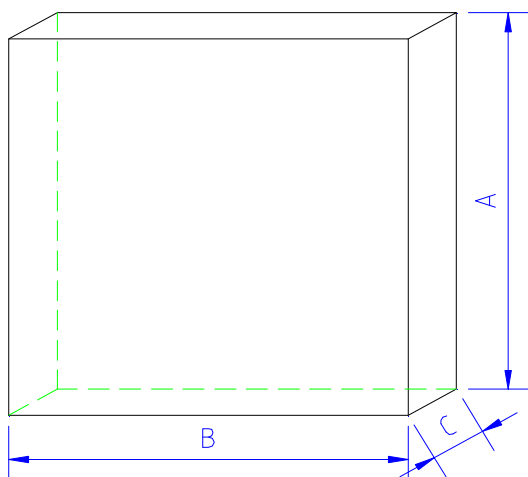
A. Reel Spec



unit: mm

SPEC	A	B	C	W	Quantity/Reel
SMA-FL 7" reel	177.0±2.0	54.0±0.5	13.0±0.5	13.2±0.2	3K
TO277 13" reel	330.0±2.0	75.0±0.5	13.0±0.5	13.2±0.2	5K
SOD123FL 7" reel	177.0±2.0	50.0±0.5	13.0±0.5	9.4±1.5	3K
SOD323HE 7" reel	177.0±2.0	50.0±0.5	13.0±0.5	9.4±1.5	3K
SMB-FL 13" reel	330.0±2.0	75.0±0.5	13.0±0.5	13.2±0.2	5K

B. 13" reel packing box



unit: mm

size	A	B	C
	335±5.0	335±2.0	40±1.0

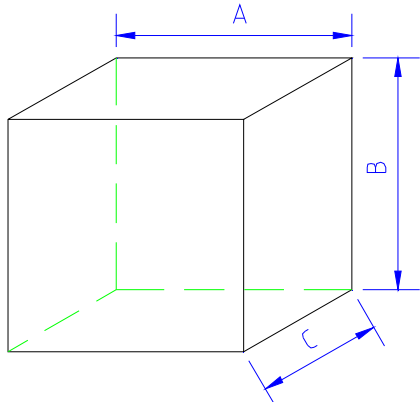
as per above packing

Spec	Q' ty/Box
TO277 13" reel	10K
SMB-FL 13" reel	10K

Title:
Power Diode SMD Package Packing Spec

DOC NO.: WI-258
DOC NO.: WI-258
Page: 3

C. 7" reel packing box



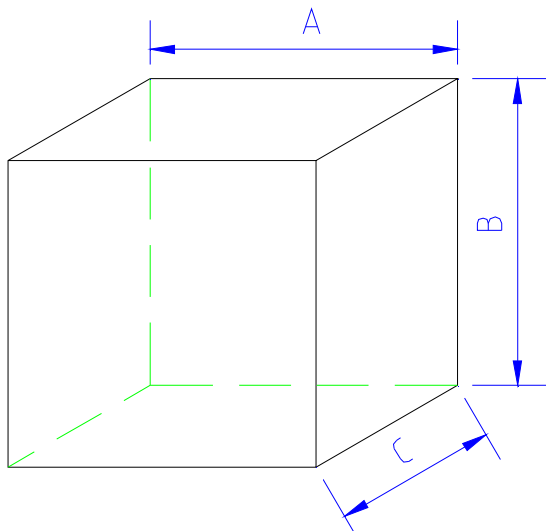
unit: mm

	A	B	C
SMA-FL SOD123FL SOD323HE	186±2.0	139±2.0	185±2.0

as per above packing

	Q' ty/Box
SMA-FL	30K
SOD123FL	30K
SOD323HE	30K

D. reel packing carton



unit: mm

	A	B	C
size	350±2.0	340±2.0	350±2.0

as per above packing

Spec	Q' ty/Carton
TO277 13" reel	80K
SMB-FL 13" reel	80K

unit: mm

	A	B	C
SMA-FL SOD123FL SOD323HE	455±2.0	400±2.0	410±2.0

as per above packing

Spec	Q' ty/Carton
SMA-FL 7" reel	360K
SOD123-FL 7" reel	360K
SOD323HE 7" reel	360K

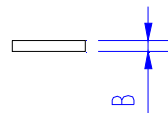
5.1.2 Tape Spec

A. Cover Tape

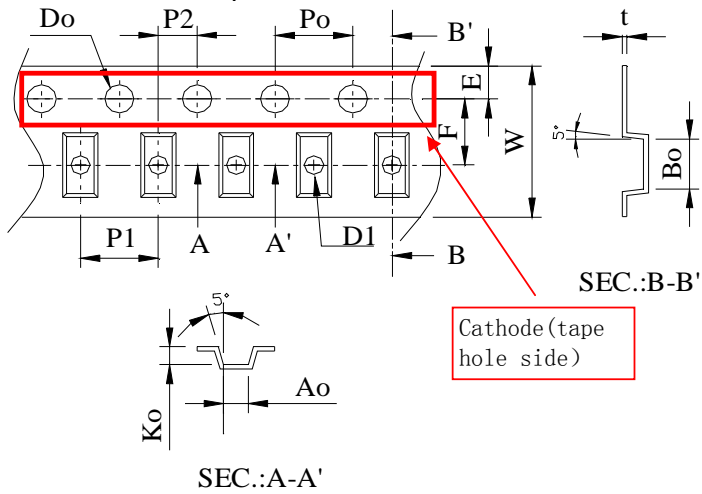


unit: mm

	A	B
SMA-FL SMB-FL TO277	9.5±0.10	0.062±0.007
SOD123FL SOD323HE	5.4±0.10	



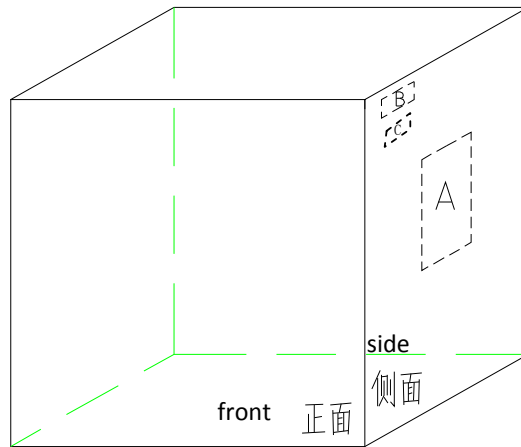
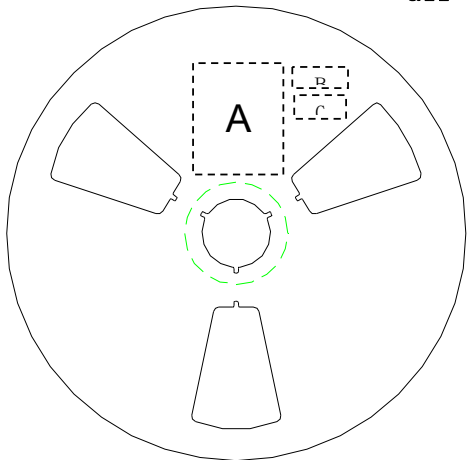
B. Carrier Tape



Item	SOD323HE	SOD123FL	SMA-FL	SMB-FL	TO277
W	8±0.3	8±0.3	12±0.3	12±0.3	12±0.3
P1	4±0.1	4±0.1	4±0.1	8±0.1	8±0.1
E	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1
F	3.5±0.05	3.5±0.05	5.5±0.05	5.5±0.05	5.5±0.05
D0	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05
D1	1.1±0.1	1.1±0.1	1.5±0.1	1.55±0.05	1.5±0.1
P0	4±0.1	4±0.1	4±0.1	4±0.1	4±0.1
P2	2±0.05	2±0.05	2±0.05	2±0.05	2±0.05
10P0	40±0.2	40±0.2	40±0.2	40±0.2	40±0.2
A0	1.45±0.1	1.95±0.1	2.83±0.1	3.8±0.1	4.3±0.1
B0	2.75±0.1	3.95±0.1	4.75±0.1	5.75±0.1	6.8±0.1
K0	0.80±0.1	1.30±0.1	1.42±0.1	1.4±0.1	1.35±0.1
T	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05

5.2、SMD Power Diode General Packing Spec

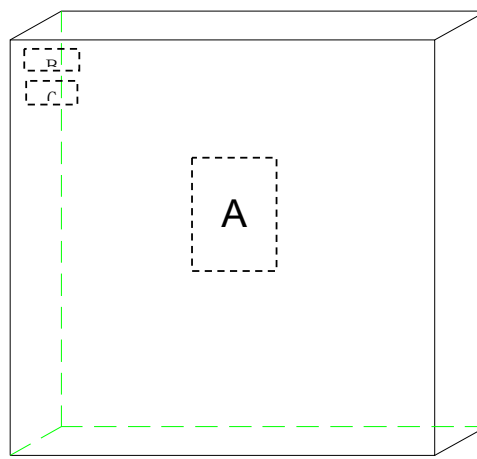
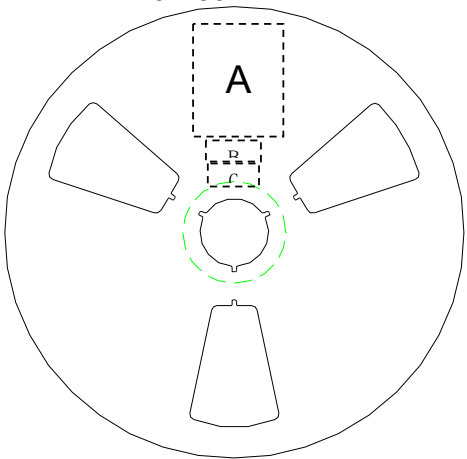
A. 7" reel all labels will be at cathode side of reel ;



A:LRC label;

B:Environment Label C:Halide free label

B. 13" reel



A:LRC label;

B:Environment Labe C:Halide free label

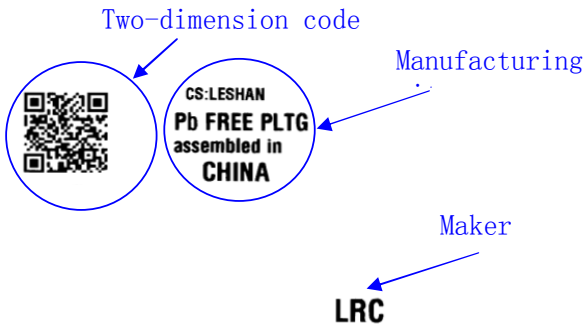
C. Tape lead: face anode side of the reel,upper side is the tape lead position. All labels are at cathode side of the reel.



标题: Power Diode SMD Package Packing Spec	DOC NO.: WI-258
	Version: 5 Modification: 0
	Page: 6

C. Label Content :
LRC Label

P/N → (1P) LPN: SM140A
 Lot No. → (1T) LOT: 140106049X
 Date code → (9D) DTE: 1403
 Quantity → (Q) QTY: 10000



lot: 140106049X: 140106---2014/1/6; 049----lot number:49; X: product code

Environment Label



Halide-free Label



LMBR120LFT1G Thru LMBR160LFT1G

7. Update Record

版次	更新记录	更新作者	更新日期
1	第一版	周杰	2013.09.03
2	1. 将LMBR120LFT1G VF由0.45V改为0.385V; 2. IR由0.03mA改为0.10mA;	周杰	2014.06.30